2024 SEMICON WEST TECHNOLOGY BREAKFAST

July 9, 2024 at 7:00 AM PT
Yerba Buena Center for the Arts, San Francisco

Mark Fuselier

Senior Vice President
Technology and Product Engineering
AMD

Mark Fuselier is senior vice president of Technology and Product Engineering at AMD. He is responsible for silicon and packaging technology development and product engineering.

Mark has more than 27 years of semiconductor industry experience and has been involved in the development and production of process technology generations spanning from 0.35µm through 4nm across multiple fabs and product families. He has played a central role in the development and productization of computing solutions such as multi-core CPU and GPU SoC integration, heterogenous APUs, 2.5D and 3D chip-packaging, and chiplet System in Package (SiP) integration.

Mark holds a Master of Science degree in electrical engineering and Master of Business Administration from the University of Texas at Austin. He is a member of IEEE and the Electron Devices Society.

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Prabu Raja, Ph.D.

President
Semiconductor Products Group
Applied Materials Fellow
Applied Materials

Dr. Prabu Raja is president of the Semiconductor Products Group (SPG) at Applied Materials where he leads semiconductor process equipment businesses and the global field organization.

Under his leadership, SPG has delivered substantial growth and is in a very strong position for the future. Since its formation, the group has expanded Applied's portfolio of co-optimized and integrated solutions to address customers' most complex and valuable problems and established the company's leadership at key inflections.

Prabu is regarded as a trusted partner by customers and has charted a remarkable career at Applied. Having joined the company as a process engineer in 1995, he demonstrated his gifts and skills as an innovator in PVD and helped secure Applied's leadership position in Metals. Over the years he led the development of many winning products, including Ionized Metal Plasma Ti/TiN and the family of Encore Tantalum and Copper products (CuBS).

In 2010, he was recognized as an Applied Fellow for his outstanding technical contributions. He also brought his drive and passion to reinvigorate the company's Etch business, which included introducing Sym3—the fastest ramping product in Applied's history. He was also instrumental in developing Applied's advanced packaging strategy, building critical ecosystem partnerships, and creating the Applied Packaging Development Center lab in Singapore.

Prabu holds a Ph.D. in plasma physics from the Indian Institute of Technology, Delhi and continued his research at the University of Iowa. He has numerous patents and publications.

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Mukund Srinivasan, Ph.D.

Group Vice President
Etch & Technology Solutions General Manager
Semiconductor Products Group
Applied Materials

Dr. Mukund Srinivasan is the Group Vice President and General Manager for the Etch Business Unit and Technology Solutions Group.

Previously, Mukund was General Manager of the CVD and ALD Business Unit within the Patterning and Packaging Group. Prior to joining Applied in January 2013, Mukund spent 16 years at Lam Research in different positions, including General Manager for the Clean Product Group and leadership positions in Etch.

He holds a Ph.D. in mechanical engineering from the University of California, Berkeley.

Mehul Naik, Ph.D.

Master and Vice President of Technology
Semiconductor Products Group
Applied Materials

Mehul Naik is a Master and Vice President of Technology with the Advanced Product Technology Development team in the Semiconductor Products Group at Applied Materials. He is responsible for the Logic Program working on inflection mapping and leading cross-functional programs in the FEOL, MEOL and Interconnect area. He has authored over 64 publications and holds over 90 U.S patents. Mehul earned his Ph.D. in chemical engineering from Rensselaer Polytechnic University.

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Sony Varghese, Ph.D.

Senior Director of Technology
Semiconductor Products Group
Applied Materials

Dr. Sony Varghese is Senior Director of Strategic Marketing for Technology in the Semiconductor Products Group at Applied Materials. In this role, he is involved in identifying challenges to scaling and future key inflections in the memory industry. Prior to Applied Materials, he worked on developing various memory technologies within the R&D organization at Micron Technology. Sony has over 35 U.S. patents issued or pending in the area of semiconductor processing and integration. He has a Ph.D. in materials and mechanical engineering from Oklahoma State University.

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Jinho An, Ph.D.

Account Technologist Director
Advanced Packaging, Semiconductor Products Group
Applied Materials

Jinho An has been serving as an Account Technologist Director in the Heterogeneous Integration Business Unit of Applied Materials since 2021. Prior to Applied, he was a process development engineer for over 10 years at Samsung's Semiconductor R&D Center and Package Development Team working on wafer level advanced packaging technology and product development including HBM, HD FOWLP and CIS. Jinho has a B.S. in inorganic materials engineering from Hanyang University and a Ph.D. in materials science and engineering from the University of Texas at Austin.

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Sarah Wozny, Ph.D.

Director
Business Development, Advanced Packaging,
Semiconductor Products Group
Applied Materials

Dr. Sarah Wozny is a Director in the Heterogeneous Integration Business Unit at Applied Materials. She focuses on wafer-level and panel-level packaging technology development.

Her areas of expertise are semiconductor manufacturing, advanced packaging and failure analysis.

Prior to joining Applied Materials in 2022, Sarah was a technologist in the Assembly, Test & Technology Development group at Intel where she developed new failure analysis and metrology techniques for nanoscale characterization of 2.5D and 3D packages. Her contributions have been recognized by several divisional and TMG excellence awards.

Sarah holds a Ph.D. in chemistry from the University of New Orleans and a B.S. in chemistry with materials from Heriot-Watt University in Scotland. She has authored and co-authored over 25 papers in peer-reviewed journals.

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Michael Sullivan

Corporate Vice President
Investor Relations
Applied Materials

Michael Sullivan is Corporate Vice President and head of Investor Relations. His team is responsible for investor relations and marketing communications including media relations, product and technology communications, and industry events.

Michael joined Applied in 2009 after working at Intel Corporation for 16 years. He was Intel's primary interface to equity analysts and the company's largest institutional shareholders in the U.S. and Europe. He also held corporate communications positions at the company's U.S. and European offices, where he drove corporate and competitive initiatives, new microprocessor introductions, computing platform campaigns and flash memory PR.

Michael is past president of the Silicon Valley chapter of NIRI, the National Investor Relations Institute. He earned his MBA at Santa Clara University and his BA in public relations at San Jose State University.